

S/N 09/901,001



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al

Examiner:

Serial No.: 09/901,001

Group Art Unit: 1756

Filed: July 9, 2001

Docket: 1303.016US1

Title: COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI
METALIZATION

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Account No. 19-0743 in order to have this Information Disclosure Statement considered.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6913

Date 6/7/2002

By Edward J. Brooks, III
Reg. No. 40,925

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 15 day of June, 2002.

Gina M Uphus

Name

Signature Gina Uphus

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COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)

Commissioner for Patents
Washington, D.C. 20231

Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/483,881	01/18/2000	00303.672US1	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
09/484,303	01/18/2000	00303.648US1	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/584,157	05/31/2000	00303.685US1	MULTILEVEL COPPER INTERCONNECT WITH DOUBLE PASSIVATION
09/817,447	03/26/2001	00303.459US2	METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN INTEGRATED CIRCUITS
09/884,540	05/14/2001	01303.013US1	COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY

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TC 1700

COMMUNICATION CONCERNING CO-PENDING APPLICATIONS

Serial Number: 09/901,001

Filing Date: July 9, 2001

Title: COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION

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MULTILEVEL COPPER
INTERCONNECTS WITH LOW-K
DIELECTRICS AND AIR GAPS

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6913

Date

7/7/2002

By

Edward J. Brooks, III
Edward J. Brooks, III
Reg. No. 40,925

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 13 day of June, 2002.

Name

Gina M. Uphus

Signature

Gina Uphus